SiC JFET Division

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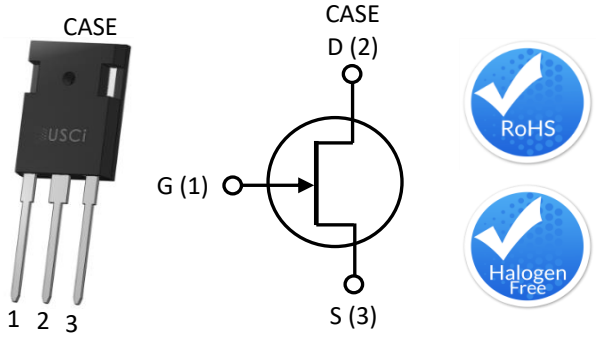
Description

United Silicon Carbide, Inc offers the high-performance G3 SiC normally-on JFET transistors. This series exhibits ultra-low on resistance ($R_{DS(ON)}$) and gate charge (Q_G) allowing for low conduction and switching loss. The device normally-on characteristics with low $R_{DS(ON)}$ at V_{GS} = 0 V is also ideal for current protection circuits without the need for active control, as well as for cascode operation.



Part Number	Package	Marking
UJ3N120070K3S	TO-247-3L	UJ3N120070K3S

Features

- Typical on-resistance $R_{DS(on),typ}$ of 70mΩ
- Voltage controlled
- Maximum operating temperature of 175°C
- Extremely fast switching not dependent on temperature
- Low gate charge
- Low intrinsic capacitance
- RoHS compliant
- AECQ Qualified

Typical Applications

- Over current protection circuits
- DC-AC inverters
- Switch mode power supplies
- Power factor correction modules
- Motor drives
- Induction heating

Maximum Ratings

Parameter	Symbol	Test Conditions	Value	Units
Drain-source voltage	V_{DS}		1200	V
Gate-source voltage	V_{GS}	DC	-20 to +3	V
		AC (1)	-20 to +20	
Continuous drain current (2)	I_D	T_C = 25°C	33.5	A
		T_C = 100°C	24.5	A
Pulsed drain current (3)	I_{DM}	T_C = 25°C	85	A
Power dissipation	P_{tot}	T_C=25°C	254	W
Maximum junction temperature	$T_{J,max}$		175	°C
Operating and storage temperature	T_J, T_{STG}		-55 to 175	°C
Max. lead temperature for soldering, 1/8" from case for 5 seconds	T_L		250	°C

(1) +20V AC rating applies for turn-on pulses <200ns applied with external R_G > 1Ω.

(2) Limited by $T_{J,max}$

(3) Pulse width t_p limited by $T_{J,max}$

Electrical Characteristics (T_J = +25°C unless otherwise specified)

Typical Performance - Static

Parameter	Symbol	Test Conditions	Value			Units
			Min	Typ	Max	
Drain-source breakdown voltage	BV_{DS}	V_{GS}= - 20V, I_D=1mA	1200			V
Total drain leakage current	I_D	V_{DS} = 1200V, V_{GS} = -20V, T_J = 25°C		5	30	µA
		V_{DS} = 1200V, V_{GS} = -20V, T_J = 175°C		18		
Total gate leakage current	I_G	V_{GS}=-20V, T_j=25°C		5	50	µA
		V_{GS}=-20V, T_j=175°C		20		
Drain-source on-resistance	$R_{DS(on)}$	V_{GS}=2V, I_D=10A, T_J = 25°C		63		mΩ
		V_{GS}=0V, I_D=10A, T_J = 25°C		70	90	
		V_{GS}=2V, I_D=10A, T_J = 175°C		139		
		V_{GS}=0V, I_D=10A, T_J = 175°C		154		
Gate threshold voltage	$V_{G(th)}$	V_{DS}= 5V, I_D = 35mA	-14	-11.5	-6	V
Gate resistance	R_G	f = 1MHz, open drain		3.3		Ω

Typical Performance - Dynamic

Parameter	symbol	Test Conditions	Value			Units
			Min	Typ	Max	
Input capacitance	C_{iss}	V_{DS} = 100V, V_{GS} = -20V, f = 100kHz		985		pF
Output capacitance	C_{oss}			100		
Reverse transfer capacitance	C_{rss}			95		
Effective output capacitance, energy related	$C_{oss(er)}$	V_{DS} = 0V to 800V, V_{GS} = -20V		52		pF
Total gate charge	Q_G	V_{DS}=800V, I_D = 25A, V_{GS}=-18V to 0V		116		nC
Gate-drain charge	Q_{GD}			63		
Gate-source charge	Q_{GS}			11		
Turn-on delay time	$t_{d(on)}$	V_{DS}=800V, I_D=25A, Gate Driver =-18V to 0V, $R_{G,EXT}$ = 1Ω, Inductive Load, FWD: UJ2D1215T T_J = 25°C		17		ns
Rise time	t_r			25		
Turn-off delay time	$t_{d(off)}$			29		
Fall time	t_f			39		
Turn-on energy	E_{ON}			434		µJ
Turn-off energy	E_{OFF}			393		
Total switching energy	E_{TOTAL}			827		
Turn-on delay time	$t_{d(on)}$	V_{DS}=800V, I_D=25A, Gate Driver =-18V to 0V, $R_{G,EXT}$ = 1Ω, Inductive Load, FWD: UJ2D1215T T_J = 150°C		17		ns
Rise time	t_r			23		
Turn-off delay time	$t_{d(off)}$			25		
Fall time	t_f			24		
Turn-on energy	E_{ON}			418		µJ
Turn-off energy	E_{OFF}			278		
Total switching energy	E_{TOTAL}			696		

Thermal Characteristics

Parameter	symbol	Test Conditions	Value			Units
			Min	Typ	Max	
Thermal resistance, junction-to-case	$R_{\theta JC}$			0.45	0.59	°C/W

Typical Performance Diagrams

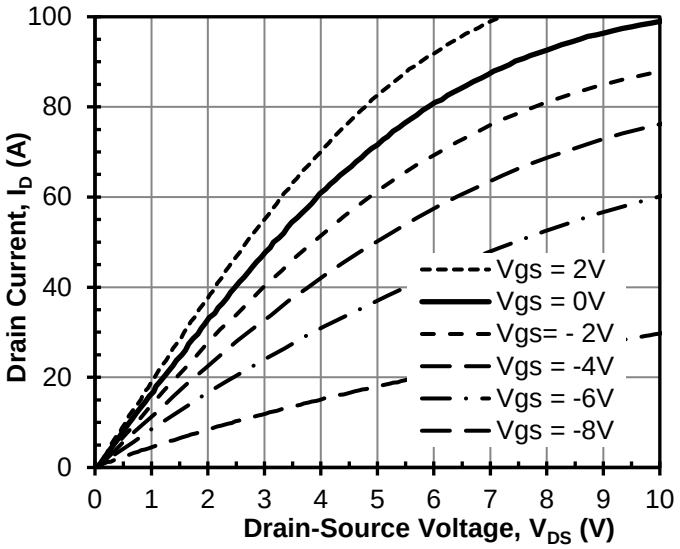


Figure 1 Typical output characteristics at T_J = -55°C

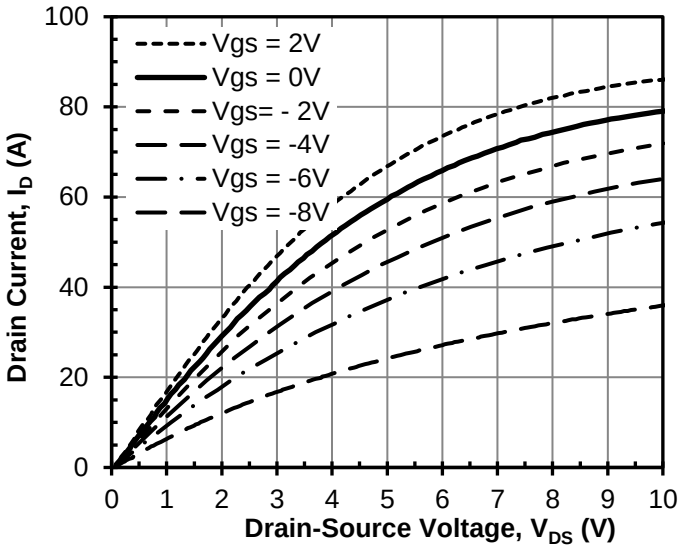


Figure 2 Typical output characteristics at T_J = 25°C

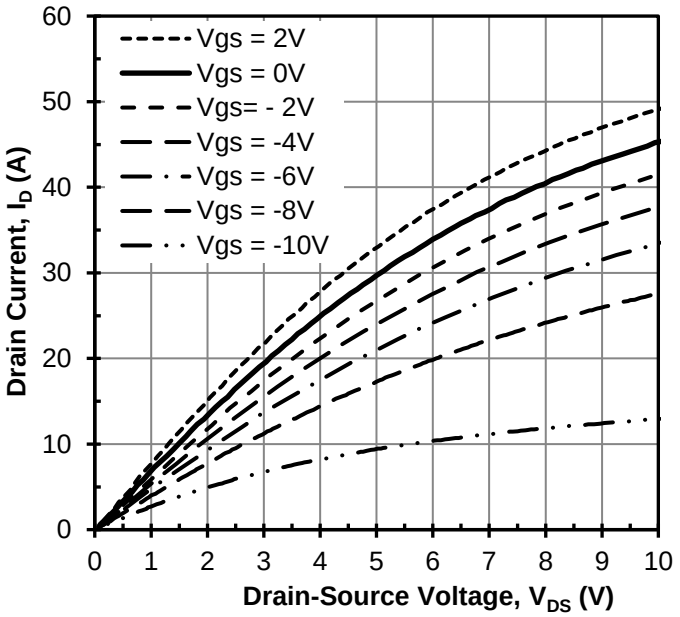


Figure 3 Typical output characteristics at T_J = 175°C

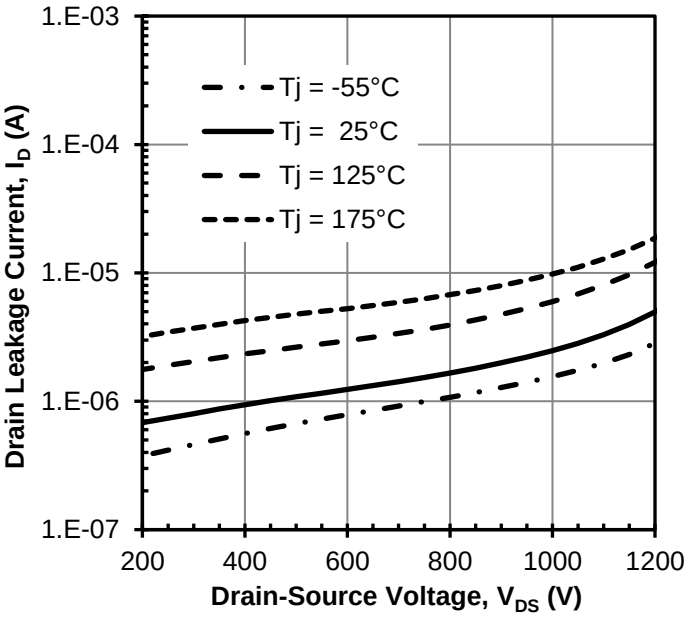


Figure 4 Typical drain-source leakage at V_{GS} = -20V

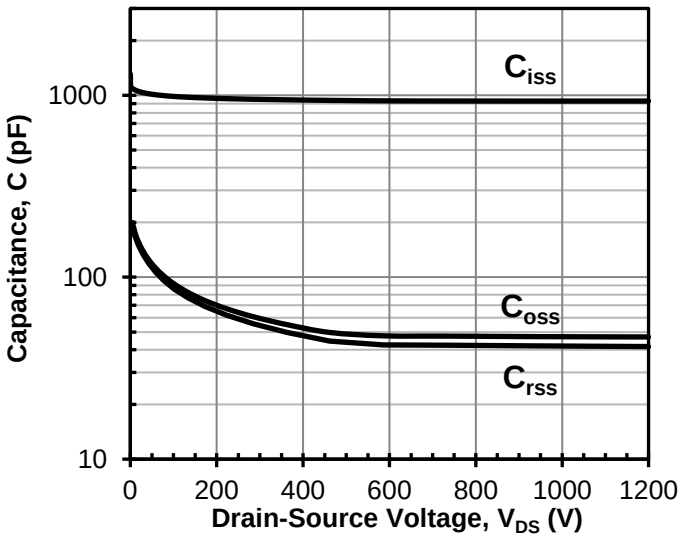


Figure 5 Typical capacitances at 100kHz and V_{GS} = -20V

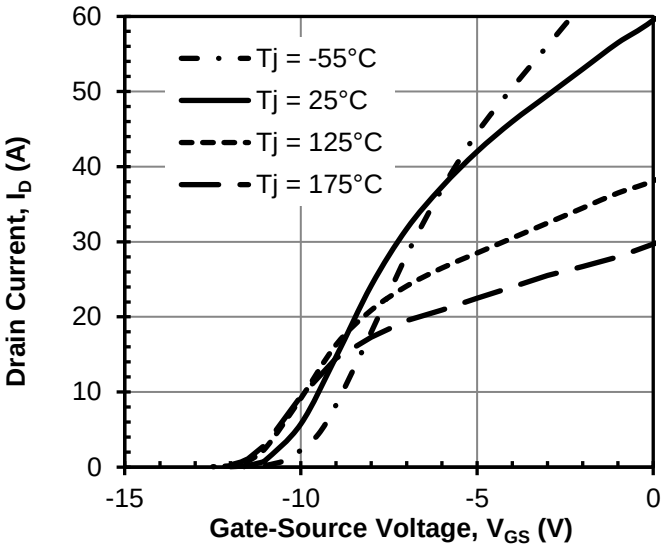


Figure 6 Typical transfer characteristics at V_{DS} = 5V

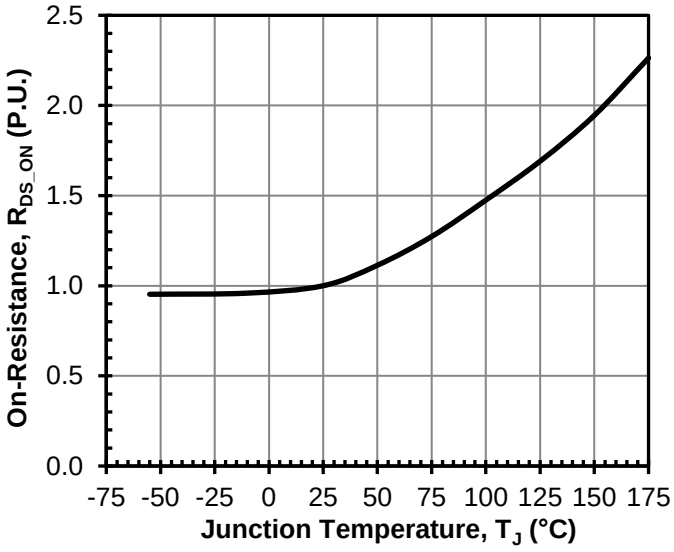


Figure 7 Normalized on-resistance vs. temperature at V_{GS} = 0V and I_D = 10A

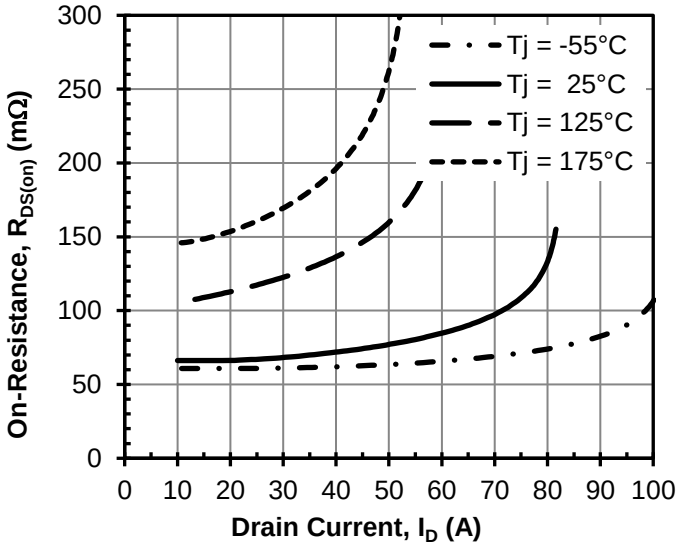


Figure 8 Typical drain-source on-resistance at V_{GS} = 0V

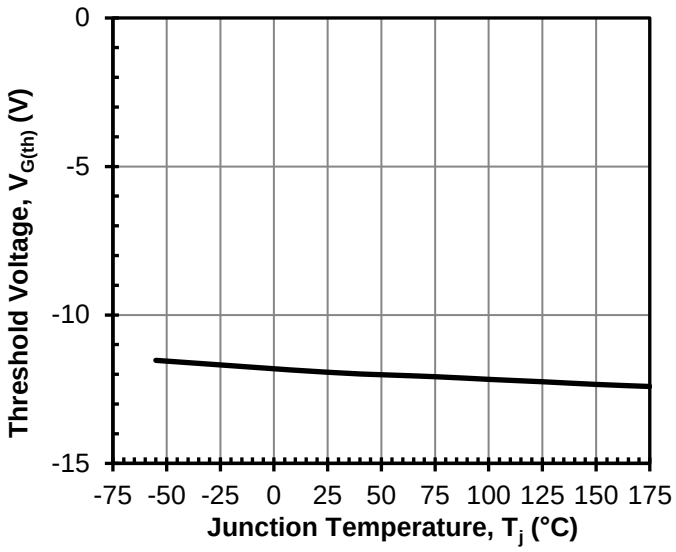


Figure 9 Threshold voltage vs. Tj at V_{DS} = 5V and I_D = 35mA

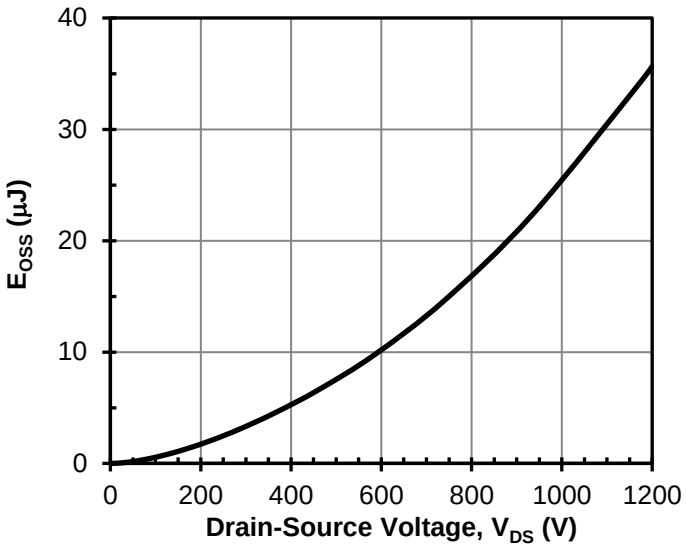


Figure 10 Typical stored energy in C_{OSS} at V_{GS} = -20V

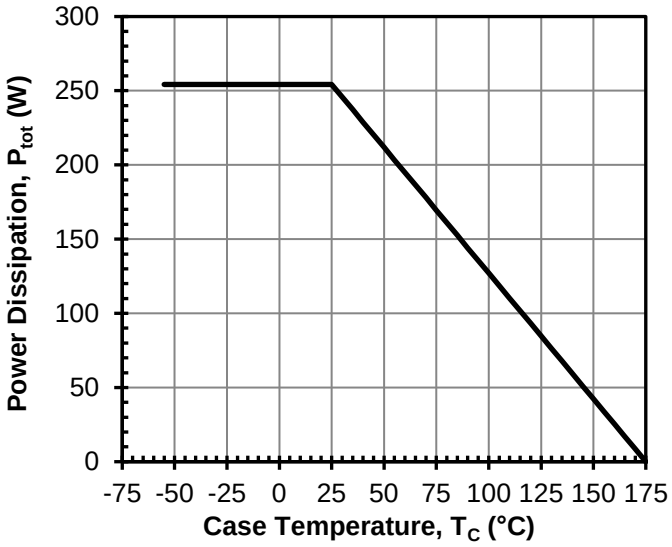


Figure 11 Total power Dissipation

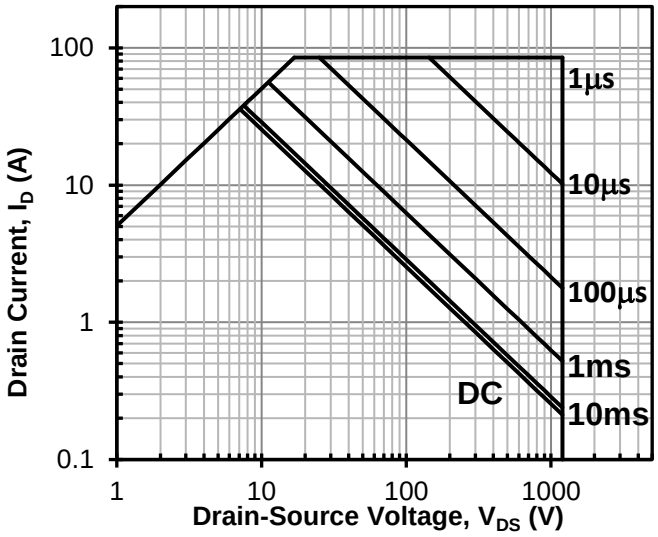


Figure 12 Safe operation area T_c = 25°C, Parameter t_p

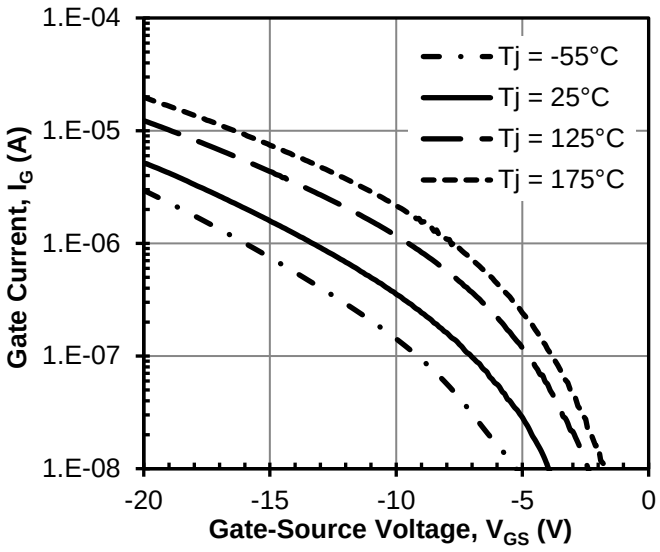


Figure 13 Typical gate leakage current at V_{DS} = 0V

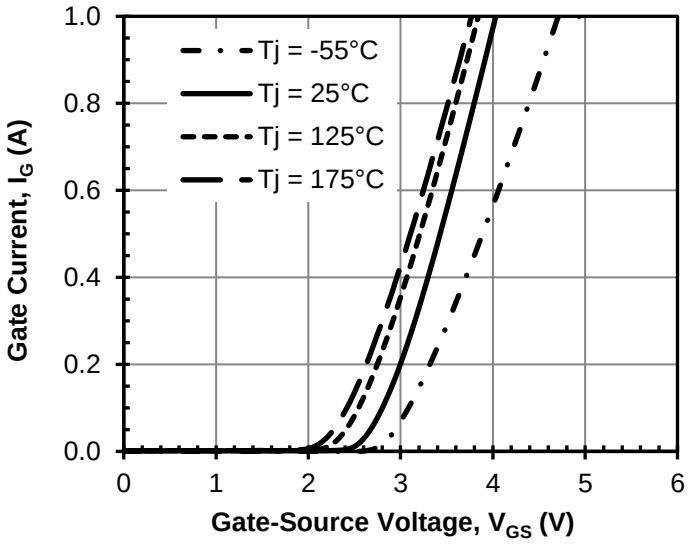


Figure 14 Typical gate forward current at V_{DS} = 0V

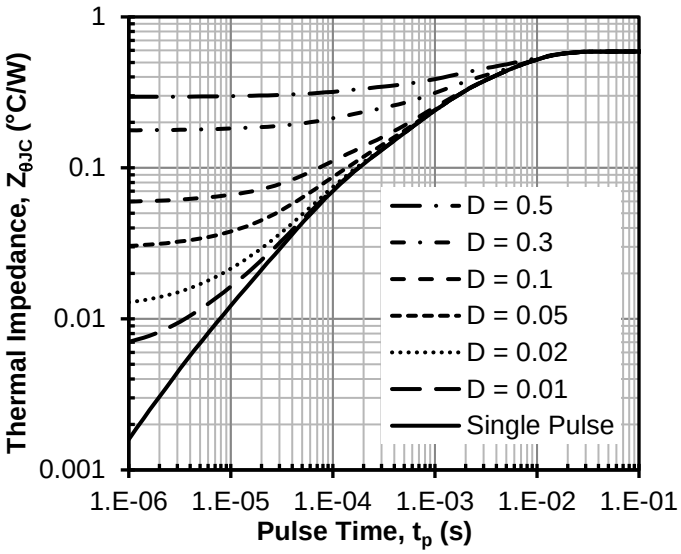


Figure 15 Maximum transient thermal impedance

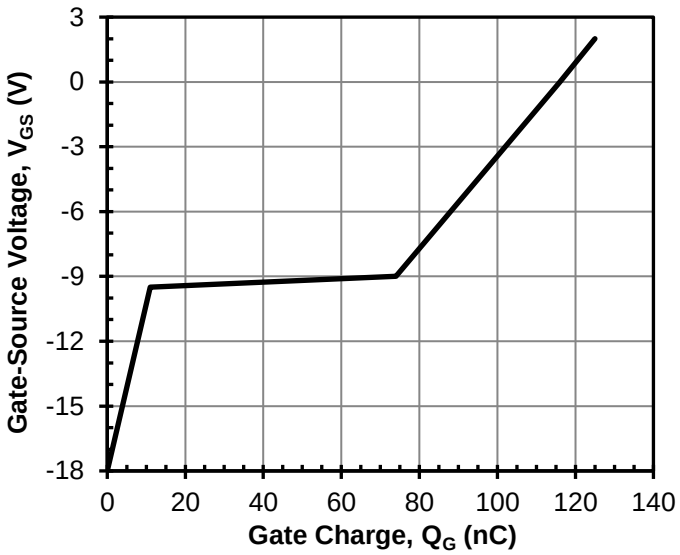


Figure 16 Typical gate charge at V_{DS} = 800V and I_D = 25A

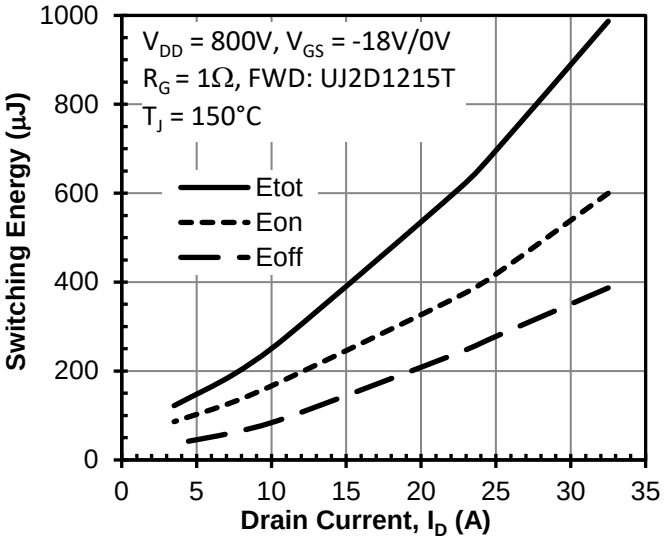


Figure 17 Clamped inductive switching energy vs. drain current at T_J = 150°C

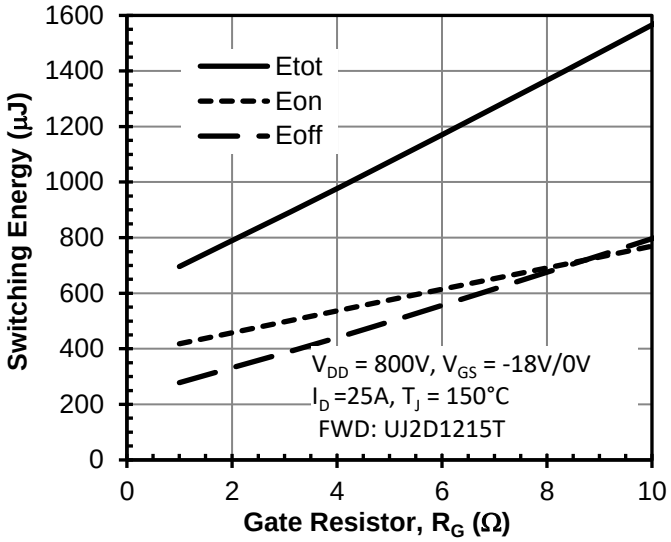


Figure 18 Clamped inductive switching energy vs. gate resistor R_G

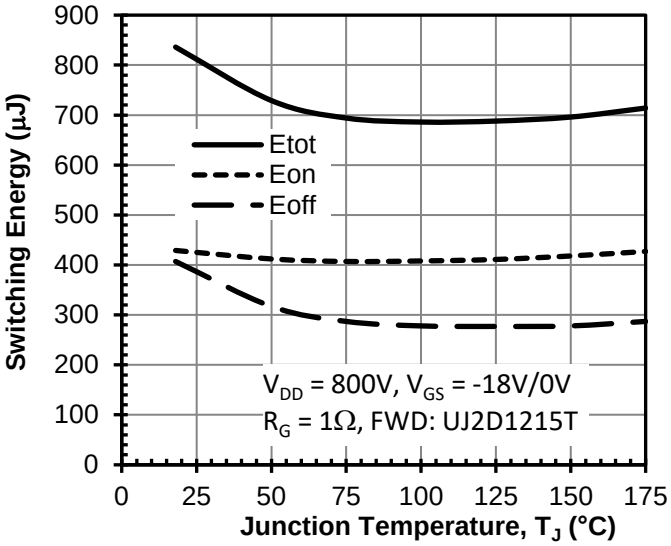


Figure 19 Clamped inductive switching energy vs. junction temperature at I_D = 25A

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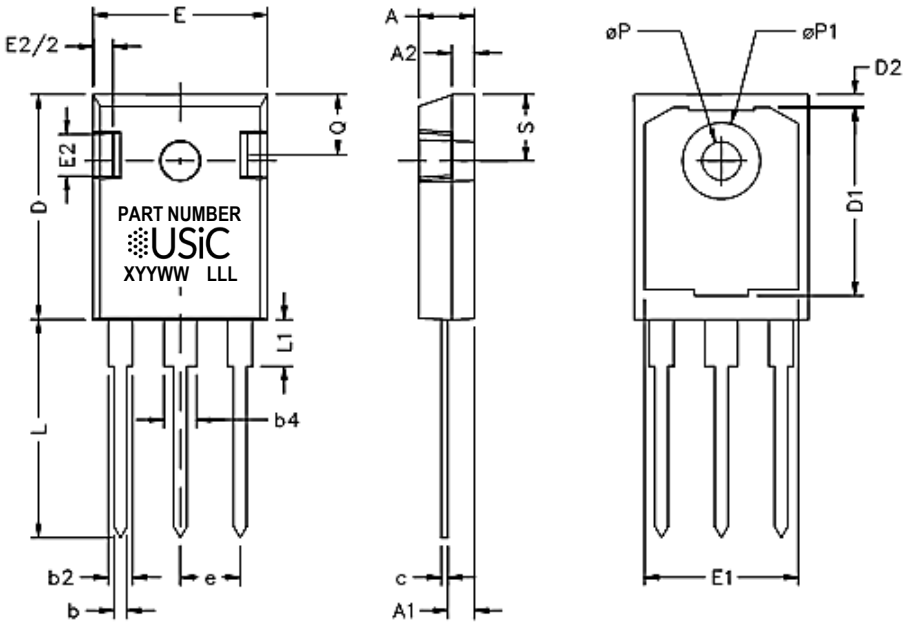
TO-247-3L PACKAGE OUTLINE, PART MARKING AND TUBE SPECIFICATIONS

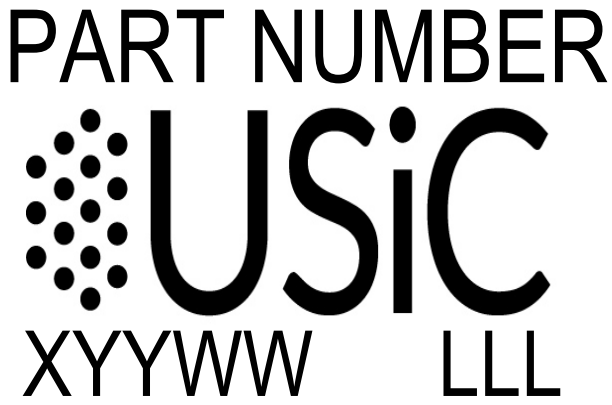
PACKAGE OUTLINE



SYM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.185	0.209	4.699	5.309
A1	0.087	0.102	2.21	2.61
A2	0.059	0.098	1.499	2.489
b	0.039	0.055	0.991	1.397
b2	0.065	0.094	1.651	2.388
b4	0.102	0.135	2.591	3.429
c	0.015	0.035	0.381	0.889
D	0.819	0.845	20.803	21.463
D1	0.515	-	13.081	-
D2	0.02	0.053	0.508	1.346
E	0.61	0.64	15.494	16.256
e	0.214 BSC		5.44 BSC	
E1	0.53	-	13.462	-
E2	0.135	0.157	3.429	3.988
L	0.78	0.8	19.812	20.32
L1	-	0.177	-	4.496
ØP	0.14	0.144	3.556	3.658
ØP1	0.278	0.291	7.061	7.391
Q	0.212	0.244	5.385	6.198
S	0.243 BSC		6.17 BSC	

TO-247-3L PACKAGE OUTLINE, PART MARKING AND TUBE SPECIFICATIONS

PART MARKING



PART NUMBER = REFER TO DS_PN DECODER FOR DETAILS

X = ASSEMBLY SITE
YY = YEAR
WW = WORK WEEK
LLL = LOT ID

PACKING TYPE

ANTI-STATIC TUBE

QUANTITY /TUBE : 30 UNITS

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